

CHM2362PT-VB Datasheet N-Channel 60-V (D-S) MOSFET

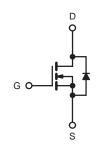
| PRODUCT SUMMARY | | | | |
|---------------------|----------------------------------|---------------------------------|-----------------------|--|
| V _{DS} (V) | R _{DS(on)} (Ω) | I _D (A) ^a | Q _g (Typ.) | |
| 60 | 0.075 at V _{GS} = 10 V | 4.0 | 2.1 nC | |
| 00 | 0.086 at V _{GS} = 4.5 V | 3.8 | 2.1110 | |

FEATURES

- Halogen-free According to IEC 61249-2-21 Available
- Trench Power MOSFET 100 % R_g Tested
- •
- 100 % UIS Tested •

APPLICATIONS

- Battery Switch
- DC/DC Converter



TO-236 (SOT23) G 1 3 D S 2 Top View

N-Channel MOSFET

| Parameter | | Symbol | Limit | Unit |
|---|------------------------|-----------------------------------|----------------------|------|
| Drain-Source Voltage | | V _{DS} | 60 | V |
| Gate-Source Voltage | | V _{GS} | ± 20 | |
| | T _C = 25 °C | | 4.0 | |
| Continuous Drain Current ($T_1 = 150 \text{ °C}$) | T _C = 70 °C | L | 3.4 | |
| Continuous Drain Current $(1) = 150^{\circ}$ C) | T _A = 25 °C | I _D | 3.1 ^{b, c} | |
| | T _A = 70 °C | | 2.5 ^{b, c} | Α |
| Pulsed Drain Current | | I _{DM} | 12 | A |
| Continuous Source Drain Diada Current | T _C = 25 °C | 1. | 1.39 | |
| Continuous Source-Drain Diode Current | T _A = 25 °C | I _S | 0.91 ^{b, c} | |
| Avalanche Current | | I _{AS} | 6 | |
| Single-Pulse Avalanche Energy | L = 0.1 mH | E _{AS} | 1.8 | mJ |
| | T _C = 25 °C | | 1.66 | |
| Maximum Dawar Dissinction | T _C = 70 °C | P _D | 1.06 | w |
| Maximum Power Dissipation | T _A = 25 °C | 'D | 1.09 ^{b, c} | V |
| | T _A = 70 °C | | 0.7 ^{b, c} | |
| Operating Junction and Storage Temperature Range | | T _J , T _{stg} | - 55 to 150 | °C |

THERMAL RESISTANCE RATINGS

| Parameter | | Symbol | Typical | Maximum | Unit | |
|---|--------------|-------------------|---------|---------|------|--|
| Maximum Junction-to-Ambient ^{b, d} | ≤ 5 s | R _{thJA} | 90 | 115 | °C/W | |
| Maximum Junction-to-Foot (Drain) | Steady State | R _{thJF} | 60 | 75 | C/VV | |

Notes:

a. Based on $T_C = 25$ °C. b. Surface Mounted on 1" x 1" FR4 board.

c. t = 5 s.

d. Maximum under Steady State conditions is 120 °C/W.



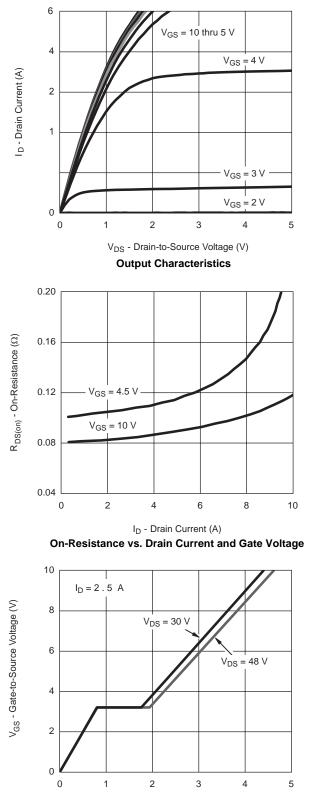
| Parameter | Symbol | Test Conditions | Min. | Тур. | Max. | Unit | |
|---|-------------------------|--|------|-------|-------|----------|--|
| Static | - | | | | • | • | |
| Drain-Source Breakdown Voltage | V _{DS} | $V_{DS} = 0 V, I_{D} = 250 \mu A$ | 60 | | | V | |
| V _{DS} Temperature Coefficient | $\Delta V_{DS}/T_{J}$ | | | 55 | | m)//0/ | |
| V _{GS(th)} Temperature Coefficient | $\Delta V_{GS(th)}/T_J$ | I _D = 250 μA | | - 5 | | mV/°C | |
| Gate-Source Threshold Voltage | V _{GS(th)} | $V_{DS} = V_{GS}, I_D = 250 \ \mu A$ | 1 | | 3 | V | |
| Gate-Source Leakage | I _{GSS} | $V_{DS} = 0 V, V_{GS} = \pm 20 V$ | | | ± 100 | nA | |
| Zana Cata Maltana Duain Cumant | 1 | $V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$ | | | 1 | <u> </u> | |
| Zero Gate Voltage Drain Current | IDSS | $V_{DS} = 60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 \text{ °C}$ | | | 10 | μA | |
| On-State Drain Current ^a | I _{D(on)} | $V_{DS} \ge 5$ V, V_{GS} = 10 V | 8 | | | А | |
| | | V _{GS} = 10 V, I _D = 1.9 A | | 0.075 | | | |
| Drain-Source On-State Resistance ^a | R _{DS(on)} | V _{GS} = 4.5 V, I _D = 1.7 A | | 0.086 | | Ω | |
| Forward Transconductance ^a | 9 _{fs} | V _{DS} = 15V, I _D = 1.9 A | | 5 | | S | |
| Dynamic ^b | | | | | 1 | 1 | |
| Input Capacitance | C _{iss} | | | 180 | | | |
| Output Capacitance | C _{oss} | | | 22 | | pF | |
| Reverse Transfer Capacitance | C _{rss} | $V_{DS} = 30 V, V_{GS} = 0 V, f = 1 MHz$ | | 13 | | | |
| T + 1 0 + 01 | Qg | $V_{DS} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 1.9 \text{ A}$ | | 4.2 | 6.1 | nC | |
| Total Gate Charge | | | | 2.1 | 3.2 | | |
| Gate-Source Charge | Q _{gs} | $V_{DS} = 30$ V, $V_{GS} = 4.5$ V, $I_{D} = 1.9$ A | | 0.7 | | | |
| Gate-Drain Charge | Q _{gd} | | | 1 | | | |
| Gate Resistance | R _g | f = 1 MHz | 0.6 | 2.2 | 5.1 | Ω | |
| Turn-On Delay Time | t _{d(on)} | | | 4 | 6 | | |
| Rise Time | t _r | $V_{DD} = 30 \text{ V}, \text{ R}_{L} = 20 \Omega$ | | 10 | 15 | - ns | |
| Turn-Off Delay Time | t _{d(off)} | $\text{I}_\text{D}\cong$ 1.5 A, V_GEN = 10 V, R_G = 1 Ω | | 10 | 15 | | |
| Fall Time | t _f | | | 7 | 10.5 | | |
| Turn-On Delay Time | t _{d(on)} | | | 15 | 23 | | |
| Rise Time | t _r | $V_{DD} = 30 \text{ V}, \text{ R}_{\text{I}} = 20 \Omega$ | | 16 | 24 | - ns | |
| Turn-Off Delay Time | t _{d(off)} | $I_{D} = 1.5 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_{G} = 1 \Omega$ | | 11 | 17 | | |
| Fall Time | t _f | | | 11 | 17 | | |
| Drain-Source Body Diode Characteristic | | | | | 1 | | |
| Continuous Source-Drain Diode Current | ۱ _S | T _C = 25 °C | | | 2.19 | • | |
| Pulse Diode Forward Current ^a | I _{SM} | | | | 7 | A | |
| Body Diode Voltage | V _{SD} | I _S = 1.5 A | | 0.8 | 1.2 | V | |
| Body Diode Reverse Recovery Time | t _{rr} | | | 15 | 23 | ns | |
| Body Diode Reverse Recovery Charge | Q _{rr} | | | 10 | 15 | nC | |
| Reverse Recovery Fall Time | t _a | I _F = 1.5 A, dl/dt = 100 A/μs, T _J = 25 °C | | 12 | | | |
| Reverse Recovery Rise Time | t _b | | | 3 | | ns | |

Notes:

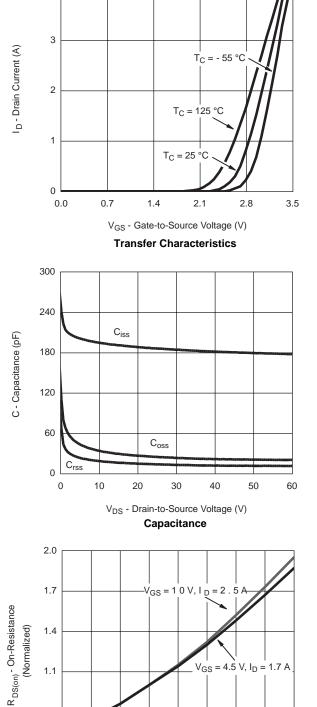
a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



4

(Normalized)

1.4

1.1

0.8

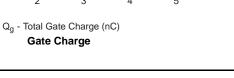
0.5

- 50

- 25

0

25



50

75

 $V_{GS} = 4.5 \text{ V}, I_D = 1.7 \text{ A}$

100

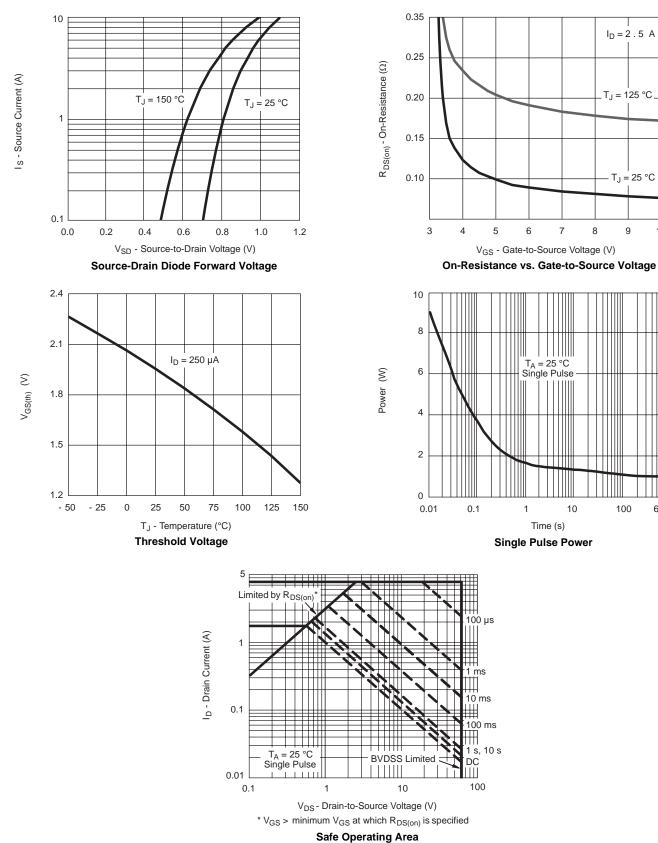
125 150



9

10

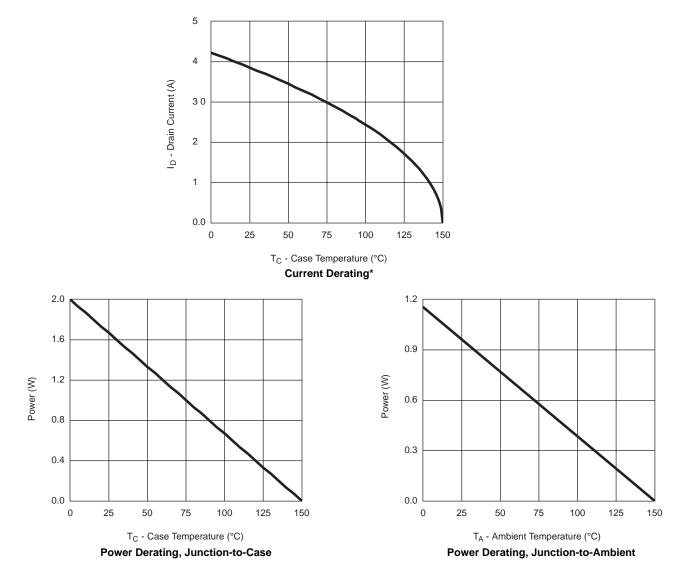
600



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

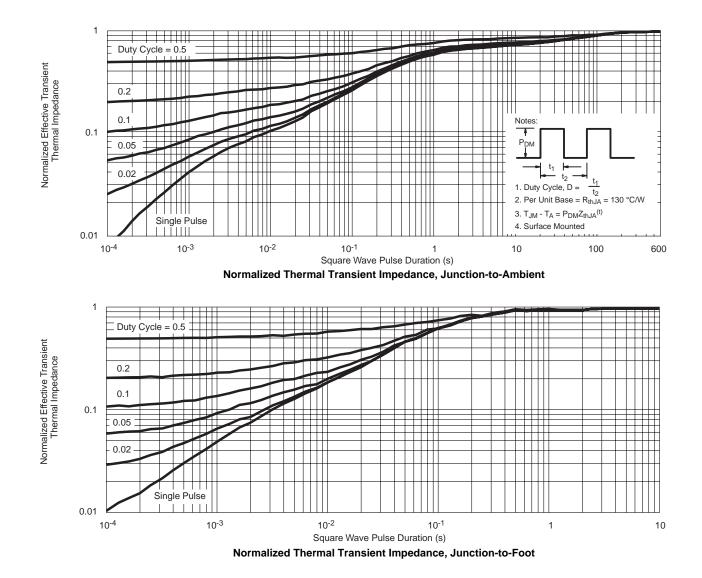


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



* The power dissipation P_D is based on $T_{J(max.)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



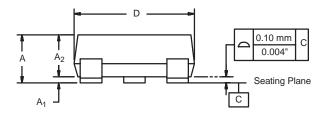


THERMAL RATINGS ($T_A = 25 \text{ °C}$, unless otherwise noted)



SOT-23 (TO-236): 3-LEAD



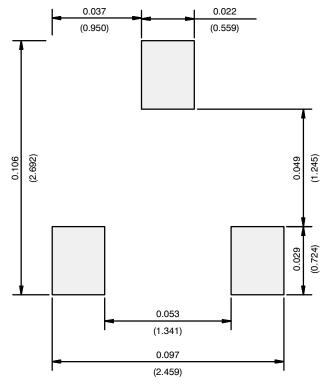




| Dim | MILLIN | IETERS | INCHES | | |
|----------------|----------|--------|------------|-------|--|
| | Min | Max | Min | Max | |
| Α | 0.89 | 1.12 | 0.035 | 0.044 | |
| A ₁ | 0.01 | 0.10 | 0.0004 | 0.004 | |
| A ₂ | 0.88 | 1.02 | 0.0346 | 0.040 | |
| b | 0.35 | 0.50 | 0.014 | 0.020 | |
| С | 0.085 | 0.18 | 0.003 | 0.007 | |
| D | 2.80 | 3.04 | 0.110 | 0.120 | |
| E | 2.10 | 2.64 | 0.083 | 0.104 | |
| E ₁ | 1.20 | 1.40 | 0.047 | 0.055 | |
| е | 0.95 BSC | | 0.0374 Ref | | |
| e ₁ | 1.90 BSC | | 0.0748 Ref | | |
| L | 0.40 | 0.60 | 0.016 | 0.024 | |
| L ₁ | 0.64 Ref | | 0.025 Ref | | |
| S | 0.50 Ref | | 0.020 Ref | | |
| q | 3° | 8° | 3° | 8° | |



RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads Dimensions in Inches/(mm)



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